

ABSTRACT

LASER REFLOW APPARATUS AND LASER REFLOW METHOD

The laser reflow apparatus of the present invention comprises a laser pressurization head module for pressing a bonding object, which includes a plurality of electronic components arranged on a substrate by a transmissive pressurization member while irradiating a laser beam through the pressurization member, to bond the electronic components to the substrate; and a bonding object transfer module for transferring the bonding object having transferred from one side of the laser pressurization head module to carry the bonding object to the other side thereof after passing through a reflow process of the laser pressurized head module.

Figure 1.